

International Application No.: PCT/JP03/02161  
U.S. Patent Application No.: Unknown  
September 1, 2004  
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**IN THE ABSTRACT:**

Please replace the Abstract of the Disclosure originally filed with the above-identified patent application with the following Abstract:

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#### ABSTRACT OF THE DISCLOSURE

A method of cutting a rare-earth alloy with a wire saw~~20~~, obtained by fixing abrasive grains ~~24~~ on a core wire ~~22~~ with a resin layer~~26~~, includes the step of moving the wire saw while a portion of the rare-earth alloy being machined with the wire saw is immersed in a coolant, which is mainly composed of water and has a surface tension of about 25 mN/m to about 60 mN/m at 25-about 25°C, thereby cutting the rare-earth alloy. In the wire saw, an average distance between two of the abrasive grains, which are adjacent to each other in a length direction, is about 150% to less than about 400% of the average grain size of the abrasive grains, an average height of portions of the abrasive grains, protruding from the surface of the resin layer, is about 70% or less of the average grain size of the abrasive grains, and a thickness deviation percentage of the resin layer with respect to the core wire is about 40%.